CLAIMS

1. A method of resin sealing of an electronic component (2) in a cavity (16) using an upper mold (13), a lower mold (14) opposite to said upper mold (13), a middle mold (15) provided between said upper mold (13) and said lower mold (14), and a release film (17) covering the cavity (16) of said lower mold (14); said method comprising the steps of:

attaching to said upper mold (13) an unsealed substrate (4) having said electronic component (2) mounted thereon;

covering a whole surface (26, 54a, 54b) of said cavity (16) with said release film (17) while said release film (17) is sandwiched between said lower mold (14) and said middle mold (15);

clamping said upper mold (13) together with said lower mold (14) and said middle mold (15) to immerse said electronic component (2) in a melting resin (6) in said cavity (16);

curing said melting resin (6) to form a cured resin (10);

opening said upper mold (13), said lower mold (14) and said middle mold (15); and

removing a sealed substrate (11) having said electronic component (2) enveloped in said cured resin (10) from said upper mold (13).

2. A mold used in the method of resin sealing of an electronic component according to claim 1.